January, 2002





Technical Specification for **Optical Transceiver Module**

	SCM6011	
155.52Mb/s Short Haul Intermediate Reach Single 5.0 V 1.3 µm Transmitter	622.08Mb/s Long Haul Long Reach Single 3.3 V 1.55 µm Receiver 2R / 3R)	other other other other other Transceiver(2 X 10) (2R / 3R)
SCI SCI	M6011-GL-ZW, SCM6011 M6011-JL-ZN, SCM6011	I-GL-CW, SCM6011-GL-DW I-JL-CN, SCM6011-JL-DN I-JL-CW, SCM6011-JL-DW
persons or damage to properties for appropriate use of with these symbols before reading this specification.	ecification uses various picture s the product. The symbols and o	rymbols to prevent possible injury to operator or other definitions are as shown below. Be sure to be familiar
<u> </u>		to human injury or property damage.
Example of picture symbols indicates prohibition	n of actions. Action details are	explained thereafter.

indicates compulsory actions or instructions. Action details are explained thereafter.

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1. General

Features of SCM6011 are listed below.

* SDH STM-1 L-1.1 / SONET OC-3 LR-1 Compliant

* Power Supply Voltage Single +3.3V

* Compact Package Size 49.0 X 13.59 X 9.8 mm (max.)

* Electrical Interface LVPECL for DATA, LVTTL for Signal Detect and Laser Disable

* Fiber Coupled Power 0 ~ -5dBm (Typ. -2dBm) into SMF

* Input Power Range -8 ~ -34dBm (Typ. Sensitivity -35dBm)

* Monitor Functions Laser Bias Monitor, Rear Facet Monitor

* Laser Disable Function

* Signal Detect (SD) Function

* Connector Interface LC Duplex Receptacle

2. Block Diagram

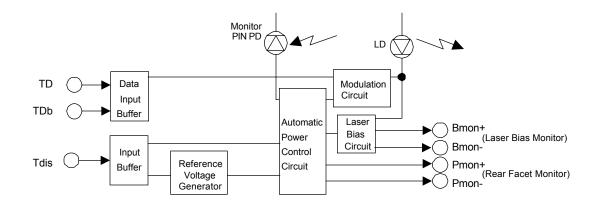


Figure 1. Block Diagram (Transmitter)

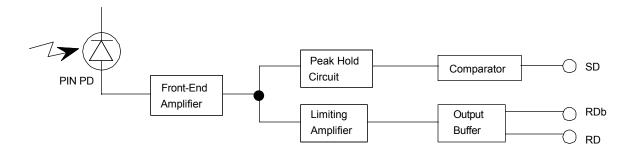


Figure 2. Block Diagram (Receiver)

∧ Caution

 $[\]gamma$ Do not disassemble this product. Otherwise, failure, electrical shock, overheating or fire may occur.

Handle the lead pins carefully. Use assisting tools or prospective aids as required. A lead pin may injure skin or human body

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3. Package Dimension

3.1 SCM6011-GL-## (With Housing Leads)

All dimensions are in mm.

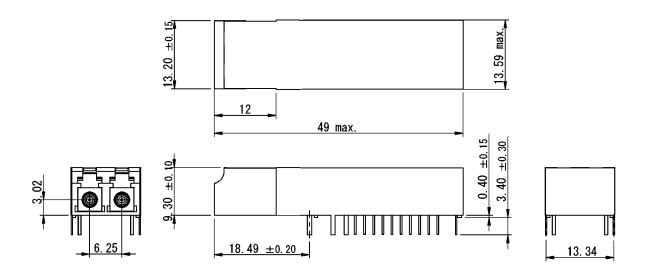
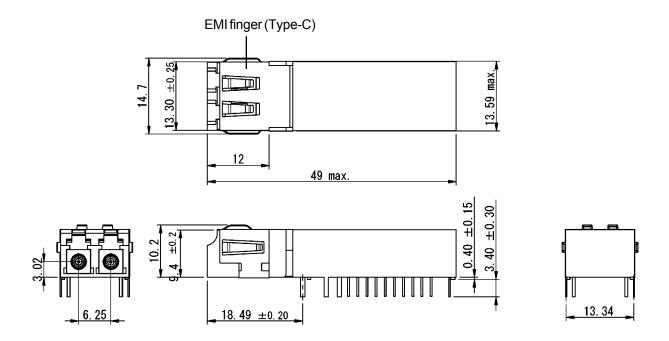


Figure 3. Outline Dimensions(SCM6011-GL-Z#)

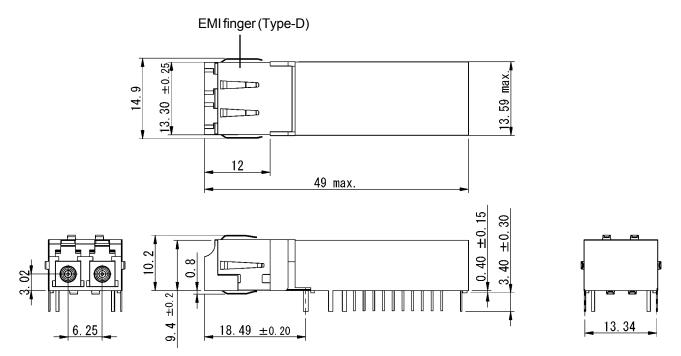


Type-C EMI finger is an option for transceivers to be used on the card-edge with the receptacle protruding through a panel opening. It has fingers on three sides to make electrical contact with the sides of the bezel opening for grounding purpose.

Figure 4. Outline Dimensions (SCM6011-GL-C#)

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All dimensions are in mm.



Type-D EMI finger is an option for transceivers to be used on the card-edge with the receptacle protruding through a panel opening. It has fingers on four sides to make electrical contact with the sides of the bezel opening for grounding purpose.

Figure 5. Outline Dimensions (SCM6011-GL-D#)

3.2 SCM6011-JL-## (Without Housing Leads)

All dimensions are in mm.

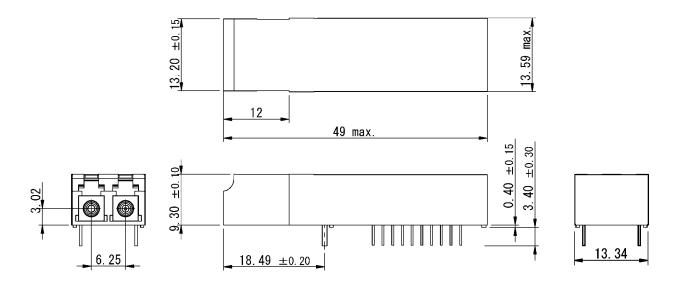
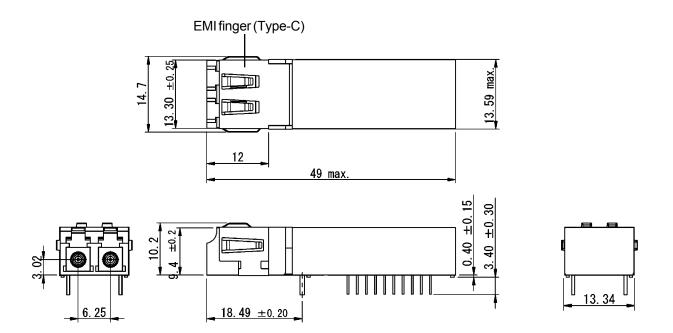


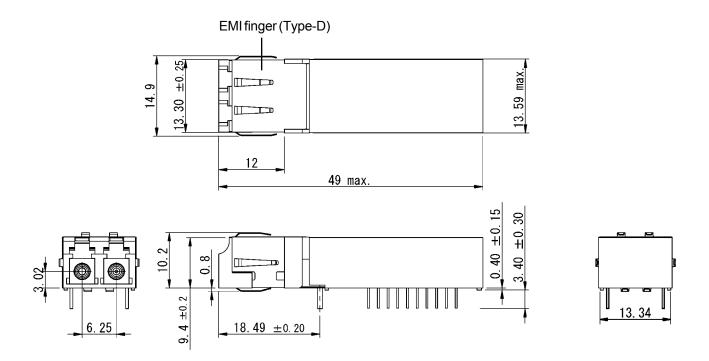
Figure 6. Outline Dimensions (SCM6011-JL-Z#)



Type-C EMI finger is an option for transceivers to be used on the card-edge with the receptacle protruding through a panel opening. It has fingers on three sides to make electrical contact with the sides of the bezel opening for grounding purpose.

Figure 7. Outline Dimensions (SCM6011-JL-C#)

All dimensions are in mm.



Type-D EMI finger is an option for transceivers to be used on the card-edge with the receptacle protruding through a panel opening. It has fingers on four sides to make electrical contact with the sides of the bezel opening for grounding purpose.

Figure 8. Outline Dimensions (SCM6011-JL-D#)

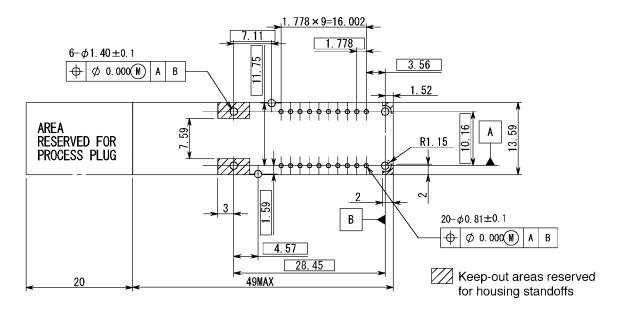


Figure 9. Recommended Footprint

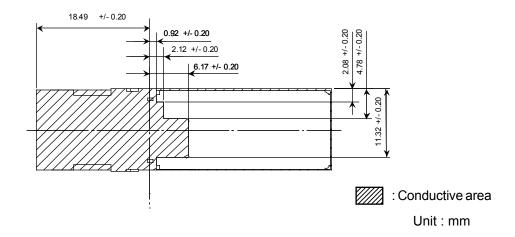


Figure 10. Package Bottom View

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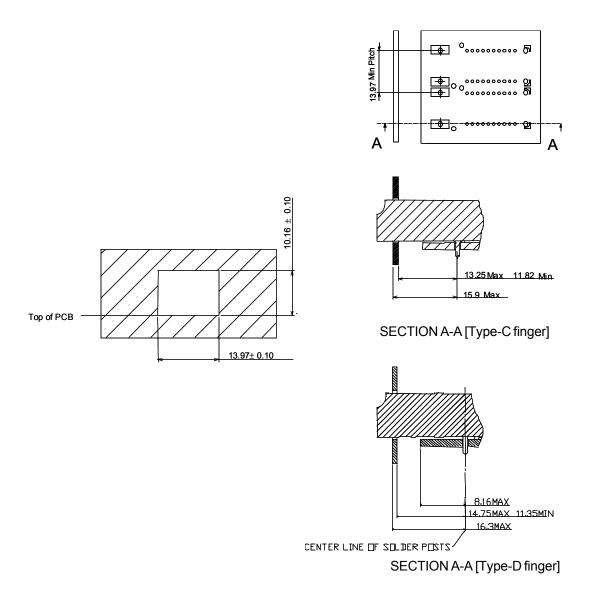


Figure 11. Recommended Bezel Design for Systems Using SFF Transceivers

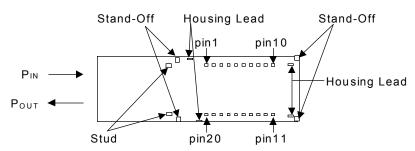
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4. Pin Assignment

No.	Symbol	I/O/P	Level	Description
1	VpdR	Р	+3.3V DC	DC Bias Supply for Receiver PIN-PD.
2	VeeR	Р	GND	Power Supply (-) for Receiver.
3	VeeR	Р	GND	Power Supply (-) for Receiver.
4	NC			No User Connections.
5	NC			No User Connections.
6	VeeR	Р	GND	Power Supply (-) for Receiver.
7	VccR	Р	+3.3V DC	Power Supply (+) for Receiver.
8	SD	0	LVTTL	Signal Detect. High level indicates presence of optical input signal (Active High).
9	RDb	0	LVPECL	Inverted Receiver Output Data. No internal terminations are provided.
10	RD	0	LVPECL	Non-Inverted Receiver Output Data. No internal terminations are provided.
11	VccT	Р	+3.3V DC	Power Supply (+) for Transmitter.
12	VeeT	Р	GND	Power Supply (-) for Transmitter.
13	Tdis	_	LVTTL/LVCMOS	Transmitter Disable (Active High). Defaults to logic 0 (enable TX) when left open.
14	TD	_	LVPECL	Non-Inverted Transmitter Input Data. Self biased. Not internally terminated.
15	TDb	ı	LVPECL	Inverted Transmitter Input Data. Self biased. Not internally terminated.
16	VeeT	Р	GND	Power Supply (-) for Transmitter.
17	Bmon-	0	Analog Voltage	LD Bias Current Monitor. Voltage difference between pins 17 and 18 is proportional
18	Bmon+	0		to the laser bias current.
19	Pmon-	0	Analog Voltage	Rear Facet Monitor. Transmitter output power can be monitored, in terms of rear
20	Pmon+	0		facet monitor PD current, by measuring voltage difference betw een pins 19 and 20.

Notes:

- 1. I/O/P stands for signal input, signal output, and DC power/bias supply, respectively.
- 2. Refer to figure 14 for details of Bmon and Pmon outputs.



- * Mounting Studs are provided for mechanical support to the circuit board.
- It is recommended that the holes in the circuit board be connected to frame ground.
- * Housing Leads are internally connected to VeeR and VeeT.

(SCM6011-JL-## has no Housing Leads.)

* Stand-Offs provide gap between the circuit board and the module to help escape residual water after aqueous wash.

Figure 12. Bottom View

5. Absolute Maximum Ratings

Parameter		Symbol	min.	Max	Unit	Note
Storage Case Temperature		Ts	-40	85	°C	1
Operating Case Teperature		Tc	-5	70	°C	2
			-40	85		3
Supply Voltage		Vcc	0.0	4.0	V	
Input Voltage		Vi	0	Vcc+0.5	V	4
Lead Soldering Conditions	Temperature	Ltemp		260	°C	5
	Time	Ltime		10	sec.	

Notes:

- 1. No condensation allowed.
- 2. SCM6011-#L-#N
- 3. SCM6011-#L-#W
- 4. TD, TDb, Tdis
- 5. Measured on lead pin at 2mm (0.079in.) off the package bottom

0

Use the product with the rated voltage described in the specification. If the voltage exceeds the maximum rating, overheating or fire may occur.

Do not store the product in the area where temperature exceeds the maximum rating, where there is too much moisture or dampness, where there is acid gas or corrosive gas, or other extreme conditions. Otherwise, failure, overheating or fire may occur.

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6. Electrical Interface

(Unless otherwise specified, Vcc = 3.135 to 3.465 V and all operating temperature shall apply.)

6-1. Transmitter side

Parameter		Symbol	min.	Тур.	Max.	Unit	Note
Supply Voltage		Vcc	3.14	3.30	3.47	V	
Supply Current		Idtx		70	150	mA	1, 2, 3
TD, TDb Input Voltage	High	Vih	Vcc-1.17		Vcc-0.73	V	4, 5, 6
	Low	Vil	Vcc-1.95		Vcc-1.45		
Signal Input Rise / Fall Time					1.5	nsec.	7
Tdis Input Voltage	High	Vdi	2.0		Vcc	V	8
	Low	Vei	0.0		8.0	V	
Tdis Input Current	High	ldi	-10	140	200	μΑ	
LD Bias Monitor Voltage		Vbm	0.01	0.05	0.50	V	2, 9
Rear Facet Monitor Volta	ge	Vrfm	0.01		0.50	V	2, 9

Notes:

- 1. Input bias current is not included. 2. 50% duty cycle data. 3. 155.52Mbps, PRBS2^23-1, NRZ. 4. Vcc=+3.3V
- 5. Tc=25°C.
- 6. Input Terminal is biased internally, as shown in the figure 13. 7. 20-80%.
- 8. LVTTL input.Refer to Section 8, "Relation between Disable Input Voltage and Optical Output Power", for detail.
- 9. The Laser Bias Monitor Current and Rear Facet Monitor Current are calculated as ratios between the corresponding voltages and current sensing resistors, 10Ω and 200Ω , as shown in the figure 14.

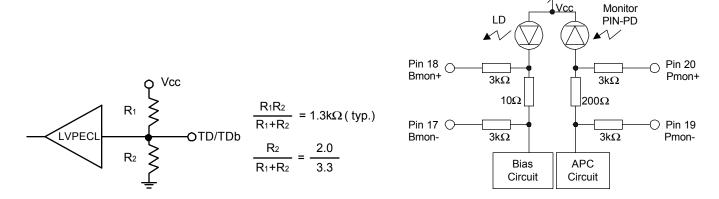


Figure 13. Internal Bias of Input Terminal

Figure 14. Bmon and Pmon Interface

6-2. Receiver side

Parameter		Symbol	min.	Тур.	Max.	Unit	Note
Supply Voltage		Vcc	3.14	3.30	3.47	V	
Supply Current		Idrx		80	140	mA	1
RD, RDb Output Voltage	High	Vdoh	Vcc-1.10		Vcc-0.86	V	2
	Low	Vdol	Vcc-1.86		Vcc-1.62		
SD Output Voltage	High	Vsoh	2.20		Vcc	V	
	Low	Vsol	0.0		0.5		
Data Rise / Fall Time	•	Trd / Tfd			1000	psec.	3
SD Assert Time		Та	2.3		100	μsec	4
SD Deassert Time		Td	2.3		100	μsec	

Notes

- 1. Output current is not included. 155.52Mbps, PRBS2^23-1, NRZ.
- 2. Vcc=+3.3V, Tc=25°C. Output load resistance RI=50 Ω to Vcc-2V for RD, RDb.
- 3. 20-80%.
- 4. 155.52Mbps, PRBS2^23-1, NRZ.

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7. Optical Interface

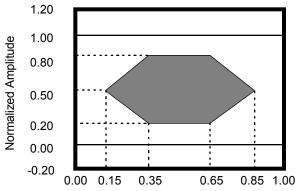
(Unless otherwise specified, Vcc = 3.135 to 3.465 V and all operating temperature shall apply.)

7-1. Transmitter side

Parameter	Symbol	min.	Тур.	Max.	Unit	Note
Average Output Power	Po	-5.0	-2.0	0.0	dBm	1
Extinction Ratio	Er	10.0			dB	1
Center Wavelength	λc	1280		1335	nm	
Spectral Width (-20dB Width)	Δλ			1.0	nm	
Side Mode Suppression Ratio	Sr	30			dB	
Eye Mask for Optical Output	Comp	Compliant with Bellcore GR-253 CORE and ITU G.957				

Notes

^{1.} Measured at 155.52Mbps PRBS2^23-1



Relation between Input Signal and Optical Output Signal

Input	Signal	Optical Output Signal
TD	TDb	
High	Low	ON (High)
Low	High	OFF (Low)
High	High	Undefined
Low	Low	Undefined

Figure 15. Optical Pulse Mask with Fourth Order

Bessel-Thomson Filter Specified in ITU-T G.957

Do not look at the laser beam projection area (e.g. end of optical connector) with naked eyes or through optical equipment while the power is supplied to this product. Otherwise, your eyes may be injured.

7-2. Receiver side

Parameter	Symbol	min.	Тур.	Max.	Unit	Note
Optical Input Wavelength	-	1261		1580	nm	
Minimum Sensitivity	Pmin		-35.0	-34.0	dBm	1, 2
Overload	Pmax	-8.0			dBm	1, 2
SD Assert Level	Pa	-45.0		-34.0	dBm	2
SD Deassert Level	Pd	-45.0		-35.0	dBm	
SD Hysteresis	Phys	1.0		6.0	dB	

Notes:

8. Relation between Disable Input Voltage and Optical Output Power

Tdis Input Voltage	Optical Output Power
"L"(0.0 ~ 0.8V)	Enabled
"H"(2.0V ~ Vcc)	Disabled (<-45dBm)
Open	Enabled

^{1.} BER=10^-10

^{2.} Measured at the bit rate of 155.52Mbps, PRBS 2^23-1, NRZ

9. Recommended Interface Circuit

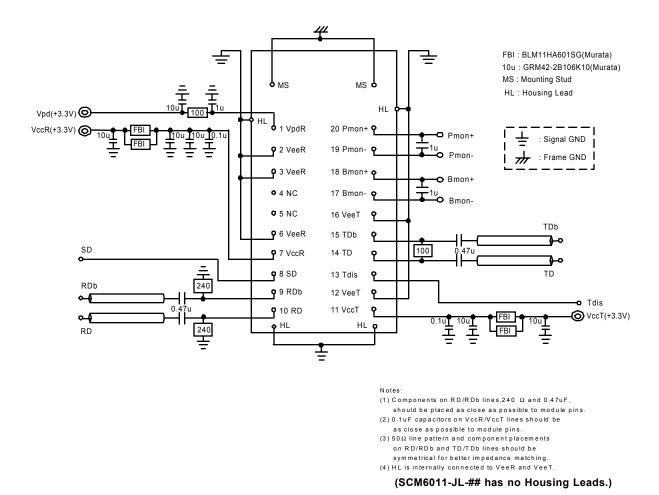


Figure 16. Recommended Interface Circuit

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10. Reliability Test Program

GR-468-CORE Issue 1, December 1998 Laser Module

HEADING	TEST	REFERENCE	CONDITIONS	SAM	1PLIN	G
				LTPD	SS	С
	Mechanical	MIL-STD-883	5 times/axis			
	Shock	Method 2002	1,500G, 0.5ms	20	11	0
Mechanical	Vibration	MIL-STD-883	Cond. A 20G, 20-2,000G	20	11	0
Integrity		Method 2007	Hz, 4min/cy, 4cy/axis			
	Thermal Shock	MIL-STD-883	Delta T=100°C	20	11	0
		Method 1011	0°C to 100°C			
	Solderability	MIL-STD-883	(steam aging not	20	11	0
		Method 2003	required)			
	Accel. Aging	(R)-4-53 Section	85°C; rated power			1
	(High Temp.)	5.18	1,000 hrs. for pass/fail	-	25	
			2,000, 5,000 hrs. for info.		10	
Endurance	Low Temp.	-	min. storage T	20	11	0
	Storage		1,000 hrs. for pass/fail			
			2,000 hrs. for info.			
	Temperature	Section 5.20	-40°C to +85°C			
	Cycling		500 for pass/fail	20	11	0
			1,000 for info.	-	11	-
	Damp Heat	MIL-STD-202	85°C/85%RH 1,000hrs.	20	11	0
		Method 103 or				
		IEC-60068-2-3				
	Cyc. Moist. Res.	Sec. 5.23	-	20	11	0
Special Tests	Internal	MIL-STD-883	Max. 5,000ppm water	20	11	0
	Moisture	Method 1018	vapour			
	ESD Threshold	Section 5.22		-	6	-

SS: Sample Size

C: Maximum number of failure allowed to pass the test.

11. Laser Safety

This product uses a semiconductor laser system and is a laser class 1 product acceptable FDA, complies with 21CFR 1040. 10 and 1040.11. Also this product is a laser class 1 product acceptable IEC 825-1.

Class 1 Laser Product

∧ Caution

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If this product is used under conditions not recommended in the specification or this product is used with unauthorized revision, classfication for laser product safety standard is invalid. Classify the product again at your responsibility and take appropriate actions.

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12. Other Precaution

Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

The governmental approval is required to export this product to other countries. To dispose of these components, the appropriate procedure should be taken to prevent illegal exportation.

This module must be handled, used and disposed of according to your company's safe working practice.

⚠ Warning



Be sure to carry out correct soldering for connection to peripheral circuits in order to prevent contact failure or short-circuit. Otherwise, a strong laser beam may cause eye injury, overheating or fire.

Do not put this product or components of this product into your mouth. This product contaions material harmful to health.



Be sure to turn the power off when you touch this product connected to the printed circuit boards. Otherwise, electric shock may occur.

Dispose this product or equipment including this product properly as an industrial waste according to the regulations.

13. Ordering Information

SCM6011 - L - L (LC Duplex Receptacle, Metallized)

Operating Case Temperature

N : Tc=-5~70°C

W: Tc=-40~85°C

EMI Shield Finger Option

Z: Without Finger

C: With Type-C Finger

D: With Type-D Finger

Housing Lead Option

G: With Housing Leads

J: Without Housing Leads

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14. For More Information

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